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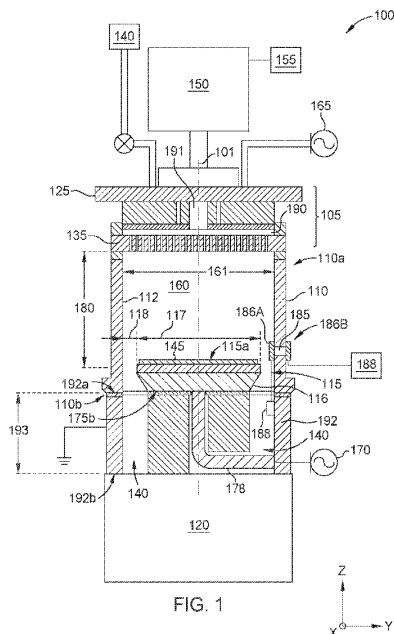
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(54) Title: SUBSTRATE PROCESSING CHAMBERS HAVING HIGH CONDUCTANCE HARDWARE



(57) Abstract: An embodiment of a processing chamber includes a chamber body having a central axis and at least partially defining a processing cavity therein. In addition, the processing chamber includes a substrate support fixed within the processing cavity. The substrate support includes an upper end portion that is configured to support a substrate thereon and a lower end portion that is spaced from the upper end portion along the central axis. The lower end portion is chamfered so as to taper toward the central axis.

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